



#### Product Summary

V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	I <sub>D</sub>
30V	0.8mΩ@10V	330A
	1.3mΩ@4.5V	

#### Feature

- Split Gate Trench Technology
- Low R<sub>DS(ON)</sub>
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

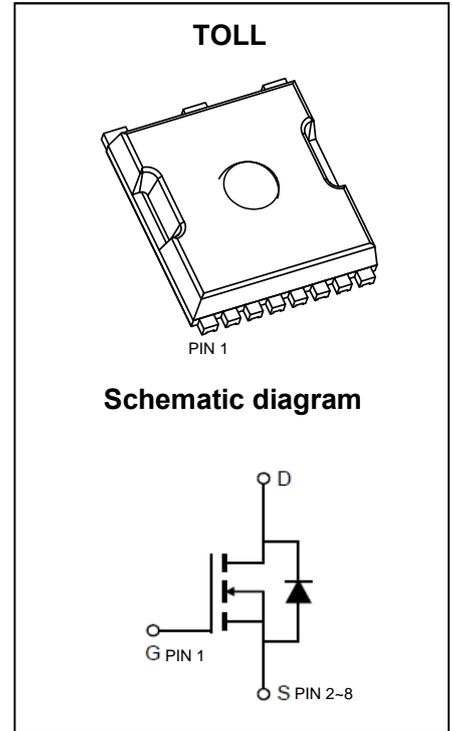
#### Application

- Power Switching Application

#### MARKING:



T008N10LTP = Device  
Code XX = Date Code  
Solid Dot = Green Indicator



#### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain - Source Voltage	V <sub>DS</sub>	30	V	
Gate - Source Voltage	V <sub>GS</sub>	±20	V	
Continuous Drain Current <sup>1</sup>	T <sub>C</sub> = 25°C	I <sub>D</sub>	330	A
	T <sub>C</sub> = 100°C	I <sub>D</sub>	214	A
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	1320	A	
Single Pulsed Avalanche Current <sup>3</sup>	I <sub>AS</sub>	48	A	
Single Pulsed Avalanche Energy <sup>3</sup>	E <sub>AS</sub>	960	mJ	
Power Dissipation <sup>5</sup>	T <sub>C</sub> = 25°C	P <sub>D</sub>	320	W
Thermal Resistance from Junction to Ambient <sup>6</sup>	R <sub>θJA</sub>	50	°C/W	
Thermal Resistance from Junction to Case	R <sub>θJC</sub>	0.47	°C/W	
Junction Temperature	T <sub>J</sub>	150	°C	
Storage Temperature	T <sub>STG</sub>	-55~ +150	°C	

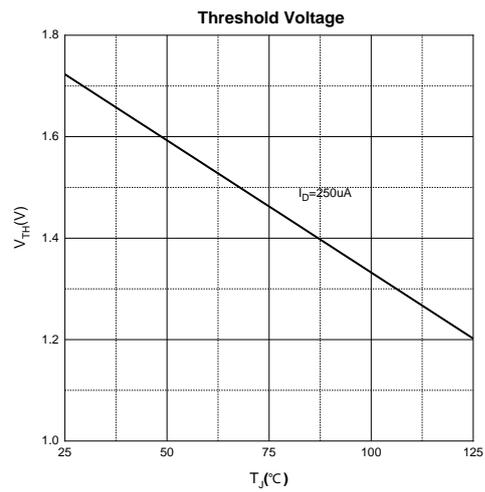
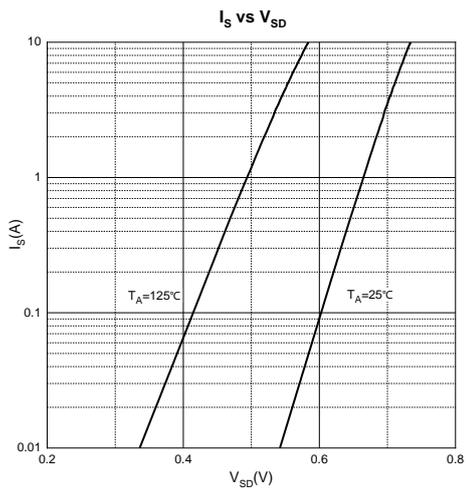
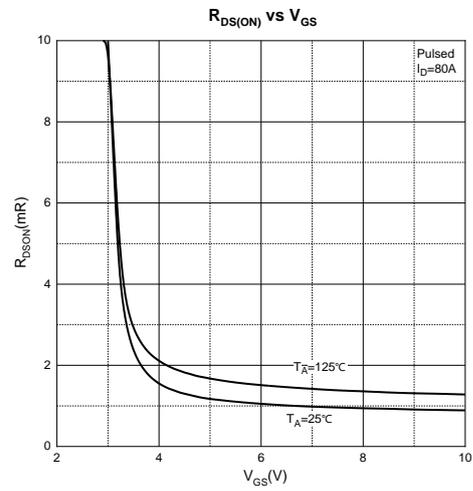
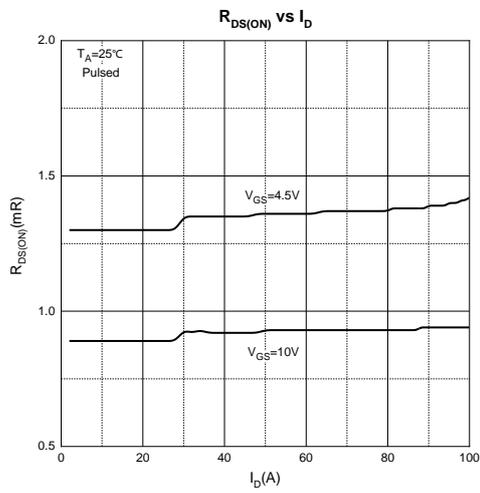
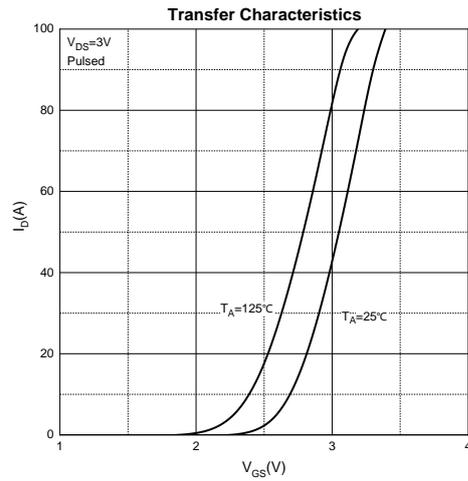
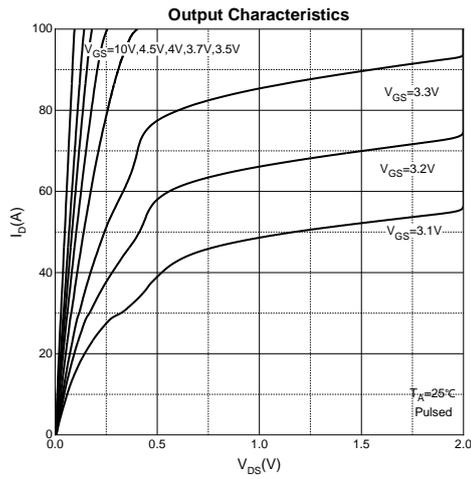
**MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**

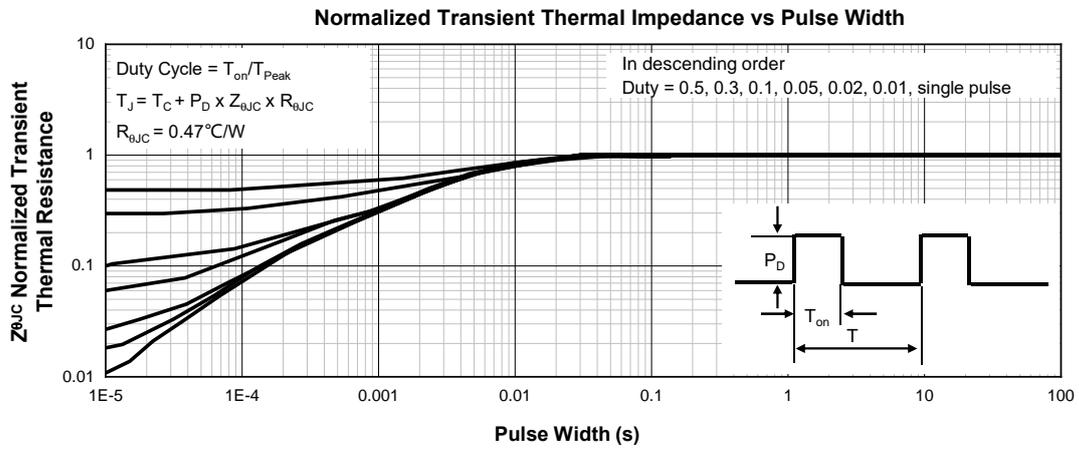
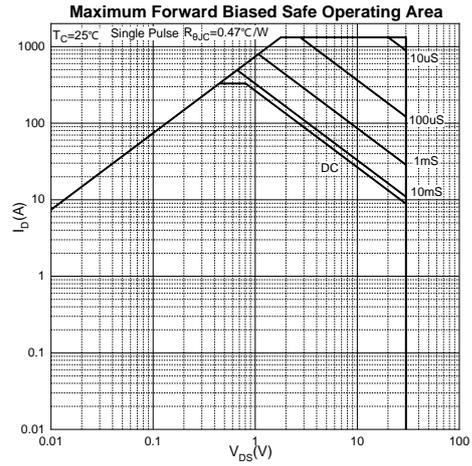
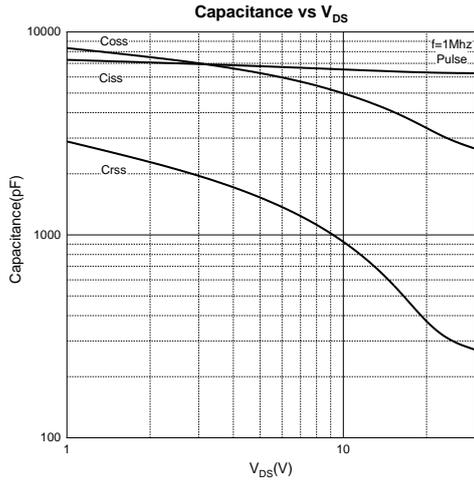
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$			1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>4</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.7	3	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$		0.8	1.2	m $\Omega$
		$V_{GS} = 4.5V, I_D = 20A$		1.3	1.8	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$		6452		pF
Output Capacitance	$C_{oss}$			3789		
Reverse Transfer Capacitance	$C_{rss}$			609		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		4.0		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DD} = 15V, V_{GS} = 10V, I_D = 20A$		118.5		nC
Gate-source Charge	$Q_{gs}$			17.4		
Gate-drain Charge	$Q_{gd}$			26.3		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V, V_{GS} = 10V, R_L = 15\Omega$ $R_G = 2.5\Omega$		18		ns
Turn-on Rise Time	$t_r$			200		
Turn-off Delay Time	$t_{d(off)}$			85		
Turn-off Fall Time	$t_f$			125		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 20A$			1.0	V

Notes :

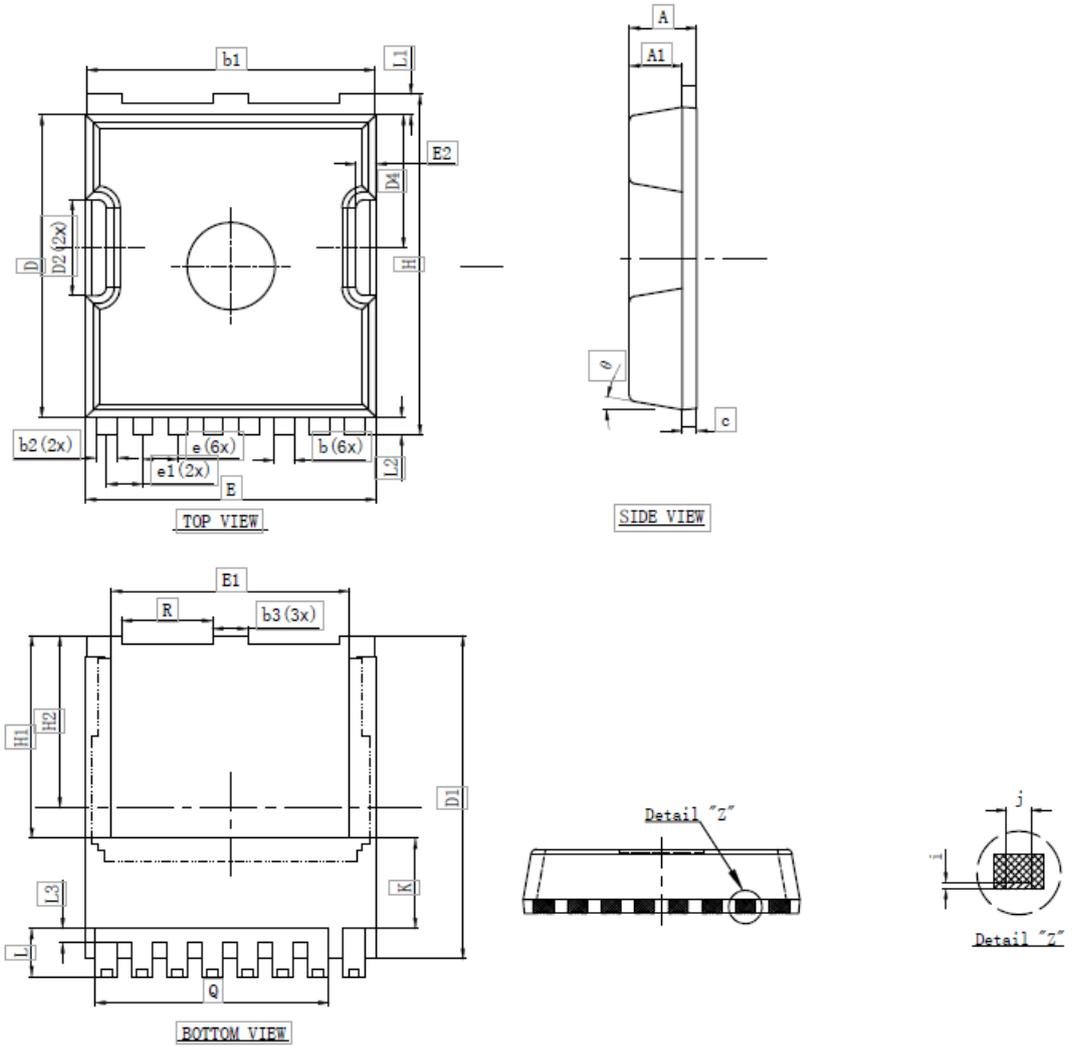
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 50V, V_{GS} = 10V, L = 1mH, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Characteristics





## TOLL Package Information



SYMBOL	MILLIMETER		Dimensions In Inches	
	MIN.	MAX.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	1.700	1.900	0.067	0.075
b	0.600	0.800	0.024	0.031
b1	9.700	9.900	0.382	0.390
b2	0.650	0.850	0.026	0.033
b3	1.100	1.300	0.043	0.051
c	0.400	0.600	0.016	0.024
D	10.300	10.500	0.406	0.413
D1	11.000	11.200	0.433	0.441
D2	3.200	3.400	0.126	0.134
D4	4.470	4.670	0.176	0.184
E	9.800	10.000	0.386	0.394